

Multilayer

20M22FR4i5i10k17

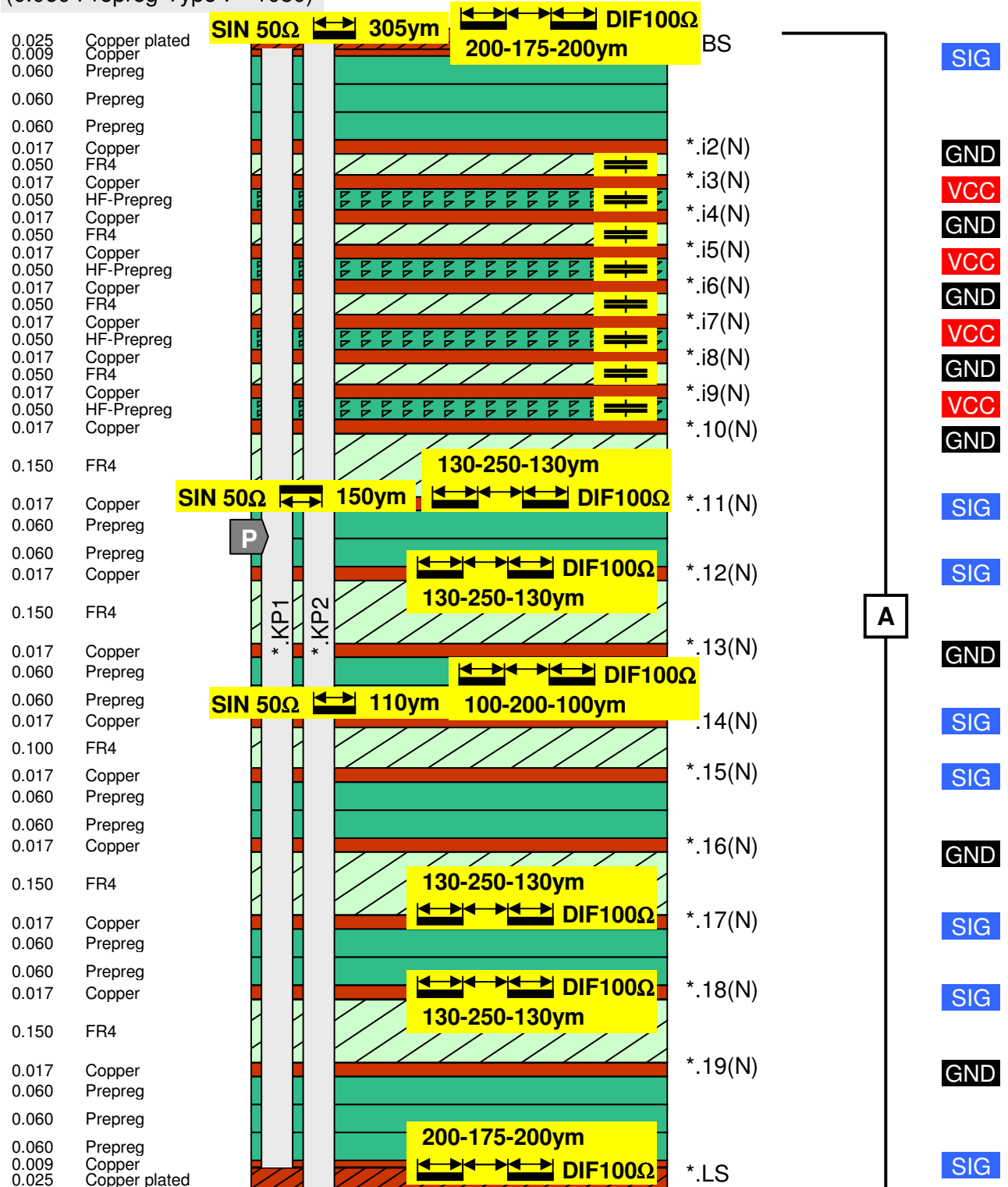
Material (mm)

Stack-Up

File

Assembly

(0.050 Prepreg-Type : 106)
(0.060 Prepreg-Type : 1080)



Thickness

(including soldermask and copperplating)

Bare Board	2.12 mm - 2.40 mm
Imm. Tin	2.21 mm - 2.50 mm
Hot-Air	2.24 mm - 2.52 mm
Imm. Gold	2.20 mm - 2.48 mm

Information



Document DOKU1886.MLT
Drawing 09.03.2005 / Wi
Revision 19.09.2008 / kra

Multilayer

14M18FR4i5i20k17v1

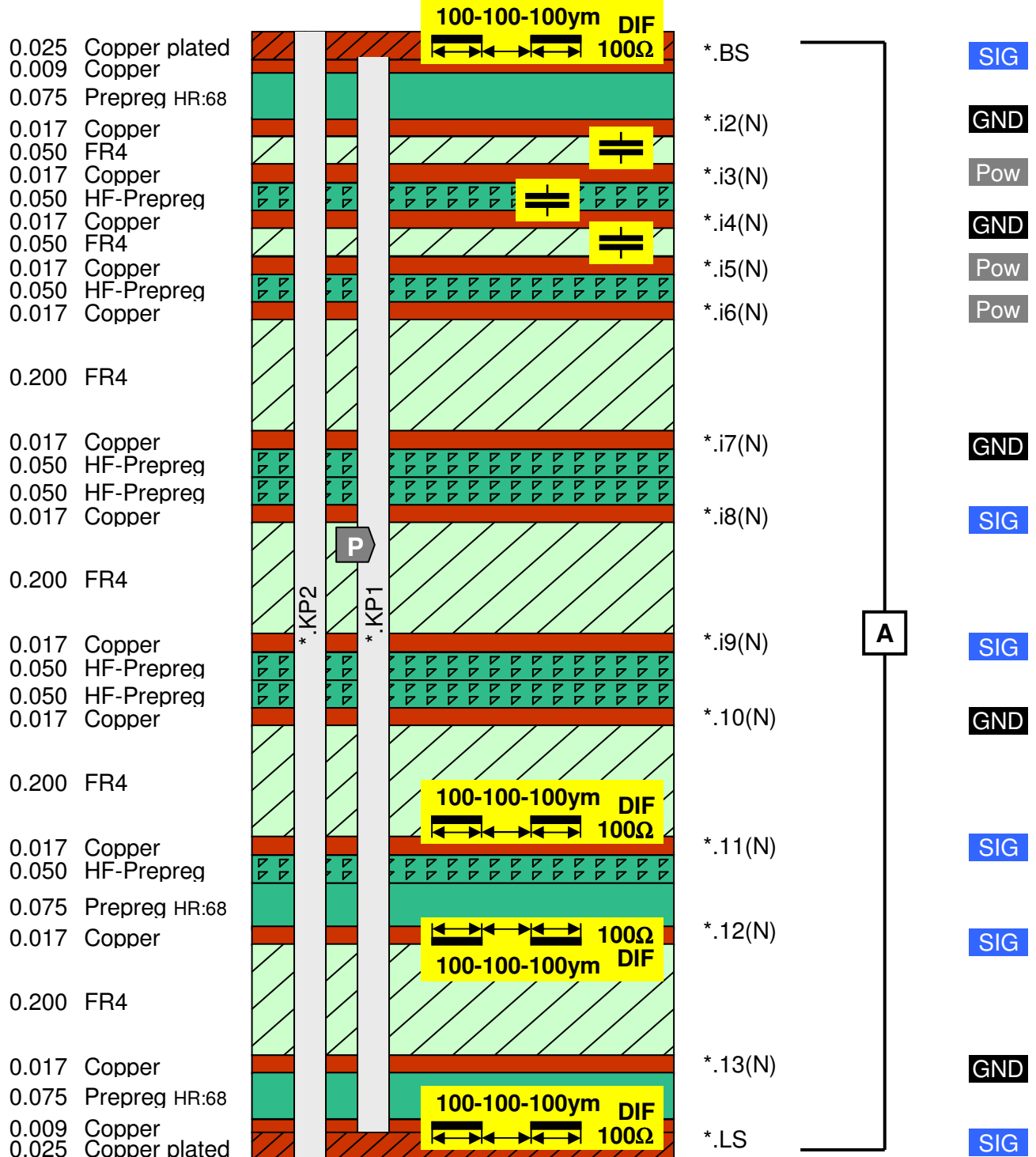
Material (mm)

Stack-Up

File

Assembly

(0.050 HF-Prepreg : 106)
(0.075 Prepreg HR68 : 1080)



Thickness

(including soldermask and copperplating)

Bare Board	1.60 mm - 1.80 mm
Immersion Tin	1.68 mm - 1.90 mm
Hot-Air	1.71 mm - 1.93 mm
Immersion Gold	1.67 mm - 1.89 mm

Information



CAM

Document
Drawing
Revision

DOKU4077.MLT
12.09.2008 / jvi

Multilayer

16M20FR4i5i15k17

Material (mm)

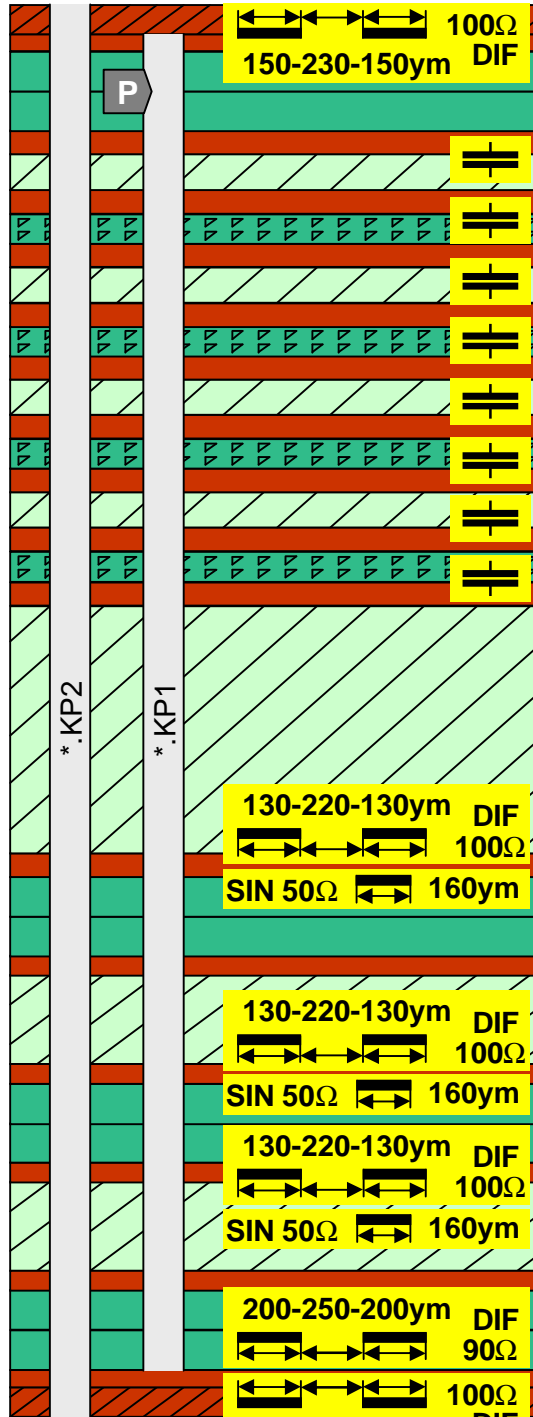
Stack-Up

File

Assembly

(0.050 HF-Prepreg : 106)
(0.060 Prepreg : 1080)

0.025 Copper plated
0.009 Copper
0.060 Prepreg
0.060 Prepreg
0.017 Copper
0.050 FR4
0.017 Copper
0.050 HF-Prepreg
0.017 Copper
0.050 FR4
0.017 Copper
0.050 HF-Prepreg
0.017 Copper
0.050 FR4
0.017 Copper
0.050 HF-Prepreg
0.017 Copper
0.050 FR4
0.017 Copper
0.050 HF-Prepreg
0.017 Copper



*.BS

SIG

*.i2(N)

GND

*.i3(N)

VCC

*.i4(N)

GND

*.i5(N)

VCC

*.i6(N)

GND

*.i7(N)

VCC

*.i8(N)

GND

*.i9(N)

VCC

*.i10(N)

GND

0.360 FR4

A

0.017 Copper
0.060 Prepreg
0.060 Prepreg
0.017 Copper

*.11(N)

SIG

0.150 FR4
0.017 Copper
0.060 Prepreg

*.12(N)

GND

0.060 Prepreg
0.017 Copper
0.150 FR4

*.13(N)

SIG

0.017 Copper
0.060 Prepreg
0.060 Prepreg
0.009 Copper
0.025 Copper plated

*.14(N)

SIG

*.15(N)

GND

*.LS

SIG

Thickness

(including soldermask and copperplating)

Bare Board	1.70 mm - 1.92 mm
Immersion Tin	1.79 mm - 2.02 mm
Hot-Air	1.82 mm - 2.05 mm
Immersion Gold	1.78 mm - 2.01 mm

Information



CAM

Document DOKU4078.MLT
Drawing 12.09.2008 / jvi
Revision 24.09.2008 / Wi